

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
Name		Execution Date	
SAJAL BIRING		01/29/2014	
RECEIVING PARTY DATA			
Name:	MATERIALS ANALYSIS TECHNOLOGY INC.		
Street Address:	1A4, NO. 1, SCIENCE-BASED INDUSTRIAL PARK		
City:	HSINCHU		
State/Country:	TAIWAN		
Postal Code:	300		
PROPERTY NUMBERS Total: 1			
Property Type	Number		
Application Number:	14175278		
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ATTORNEY DOCKET NUMBER:	4647-111		
NAME OF SUBMITTER:	BENJAMIN J. HAUPTMAN		
Signature:	/Benjamin J. Hauptman/		
Date:	02/07/2014		
Total Attachments: 1 source=Assignment#page1.tif			

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-----------------|----|
| 1) Sajal Biring | 4) |
| 2) | 5) |
| 3) | 6) |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

Materials Analysis Technology Inc. having a place of business at 1A4, No.1, Science-Based Industrial Park, Hsinchu, Taiwan, 300; and their successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

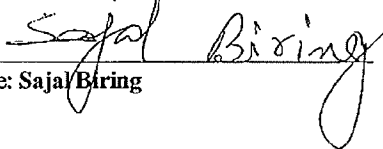
Dimension Calculation Method for a Semiconductor Device

- (a) for which an application for United States Letters Patent was filed on _____, and identified by United States Patent Application No. _____; or
- (b) for which an application for United States Letters Patent was executed on January 29, 2014.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) 
Name: Sajal Biring

Date: January 29, 2014

2) _____
Name:

Date:

3) _____
Name:

Date: